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XINBOLE

Product Specification

XBLW 15N10

N-Channel Enhancement Mode MOSFET

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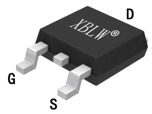
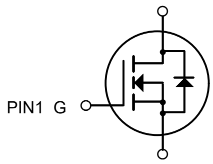
RoHS

General Description

The 15N10 uses advanced trench technology and esign to provide excellent RDS(ON) with low gate charge. It can be used in a wide variety of applications.



TO−252−2L



N-Channel MOSFET

Features

- VDS =100V,ID = 15A
- RDS(ON) <112mΩ @ VGS=10V

Applications

- Power switch
- DC/DC converters

Ordering Information

Product Model	Package Type	Marking	Packing	Packing Qty
XBLW 15N10	TO-252-2L	15N10	Tape	2500Pcs/Reel

Absolute Maximum Ratings (TC=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	±20	V
I_D@T_C=25˚C	Continuous Drain Current, V_{GS} @ 10V [1]	15	A
I_D@T_C=100˚C	Continuous Drain Current, V_{GS} @ 10V [1]	7.7	A
I_D@T_A=25˚C	Continuous Drain Current, V_{GS} @ 10V [1]	3	A
I_D@T_A=70˚C	Continuous Drain Current, V_{GS} @ 10V [1]	2.4	A
I_{DM}	Pulsed Drain Current[2]	24	A
EAS	Single Pulse Avalanche Energy[3]	6.1	mJ
I_{AS}	Avalanche Current	11	A
P_D@T_C=25˚C	Total Power Dissipation[3]	34.7	W
P_D@T_A=25˚C	Total Power Dissipation[3]	2	W
T_{STG}	Storage Temperature Range	-55 to 150	˚C
T_J	Operating Junction Temperature Range	-55 to 150	˚C
$R_{\theta JA}$	Thermal Resistance Junction-ambient [1]	62	˚C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case[1]	3.6	˚C/W

Electrical Characteristics (TJ=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	100	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BVDSS Temperature Coefficient	Reference to 25°C , I_D=1mA	---	0.098	---	V/°C
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V , I_D=10A	---	100	112	mΩ
		V_{GS}=4.5V , I_D=8A	---	117	130	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	1.0	---	2.5	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-4.57	---	mV/°C
I_{DSS}	Drain-Source Leakage Current	V_{DS}=80V , V_{GS}=0V , T_J=25°C	---	---	1	uA
		V_{DS}=80V , V_{GS}=0V , T_J=55°C	---	---	5	
I_{GSS}	Gate-Source Leakage Current	V_{GS}= ±20V , V_{DS}=0V	---	---	±100	nA
gfs	Forward Transconductance	V_{DS}=5V , I_D=10A	---	13	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	2	---	Ω
Q_g	Total Gate Charge (10V)	V_{DS}=80V , V_{GS}=10V , I_D=10A	---	26.2	---	nC
Q_{gs}	Gate-Source Charge		---	4.6	---	
Q_{gd}	Gate-Drain Charge		---	5.1	---	
$T_{d(on)}$	Turn-On Delay Time	V_{DD}=50V , V_{GS}=10V , R_G=3.3 I_D=10A	---	4.2	---	ns
T_r	Rise Time		---	8.2	---	
$T_{d(off)}$	Turn-Off Delay Time		---	35.6	---	
T_f	Fall Time		---	9.6	---	
C_{iss}	Input Capacitance	V_{DS}=15V , V_{GS}=0V , f=1MHz	---	1535	---	pF
C_{oss}	Output Capacitance		---	60	---	
C_{rss}	Reverse Transfer Capacitance		---	37	---	
I_S	Continuous Source Current[1,5]	V_G=V_D=0V , Force Current	---	---	12	A
I_{SM}	Pulsed Source Current[2,5]		---	---	24	A
V_{SD}	Diode Forward Voltage[2]	V_{GS}=0V , I_S=1A , T_J=25°C	---	---	1.2	V
t_{rr}	Reverse Recovery Time	I_F=10A , dI/dt=100A/μs , T_J=25°C	---	37	---	nS
Q_{rr}	Reverse Recovery Charge		---	27.3	---	nC

Note :
1.The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%

3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=11A
4.The power dissipation is limited by 150°C junction temperature

5 .The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

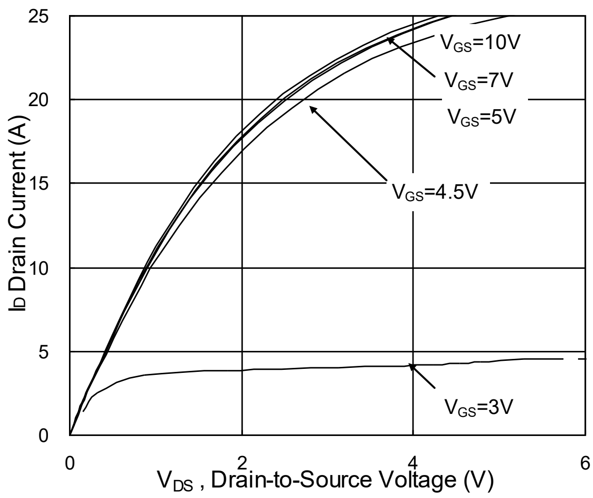


Fig.1 Typical Output Characteristics

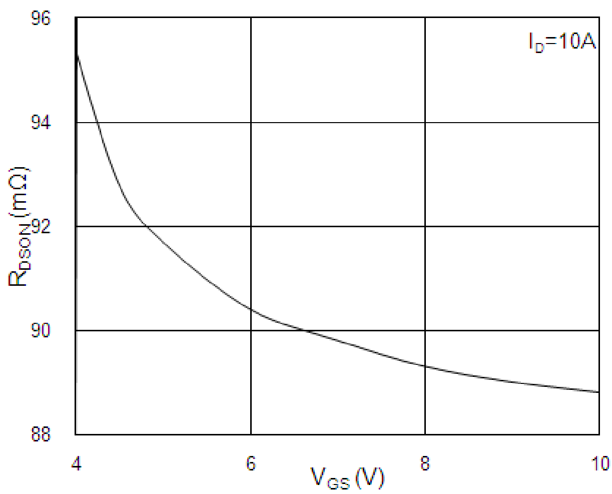


Fig.2 On-Resistance vs. Gate-Source

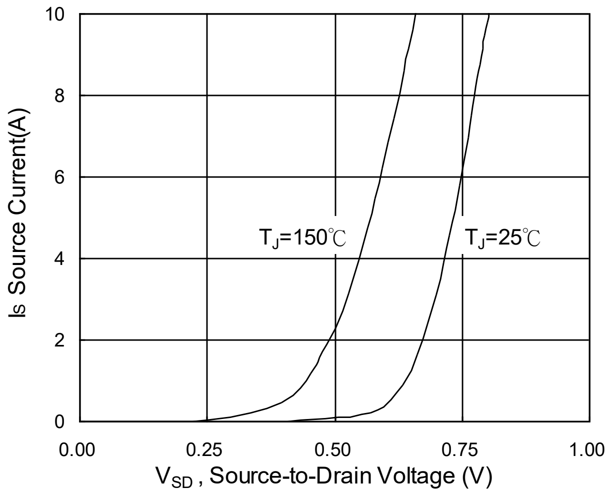


Fig.3 Forward Characteristics Of Reverse

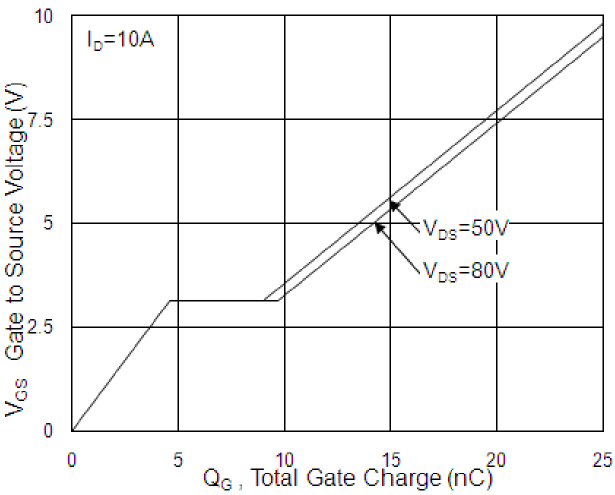


Fig.4 Gate-Charge Characteristics

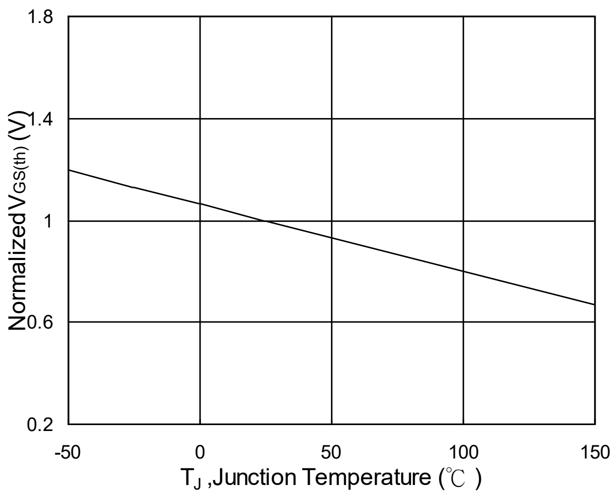


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

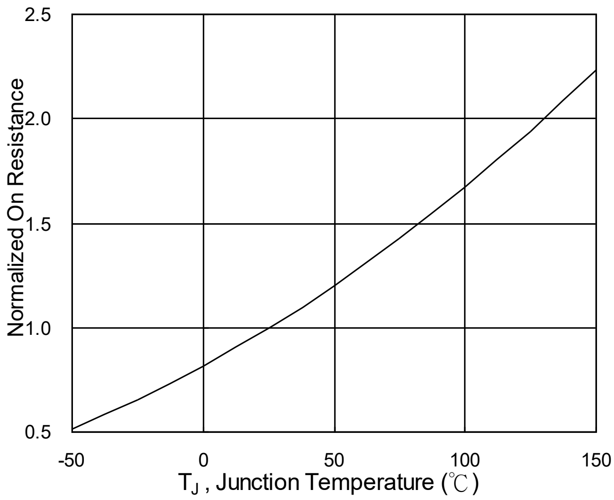


Fig.6 Normalized R_{DSON} vs. T_J

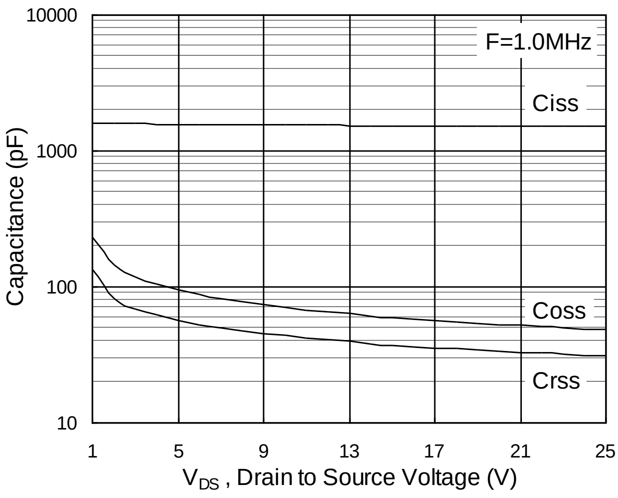


Fig.7 Capacitance

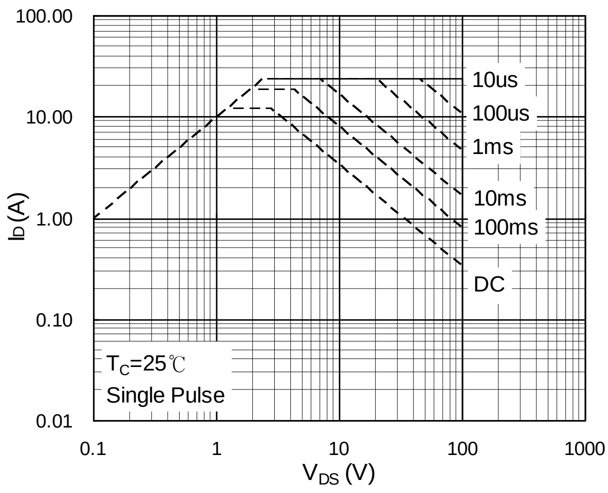


Fig.8 Safe Operating Area

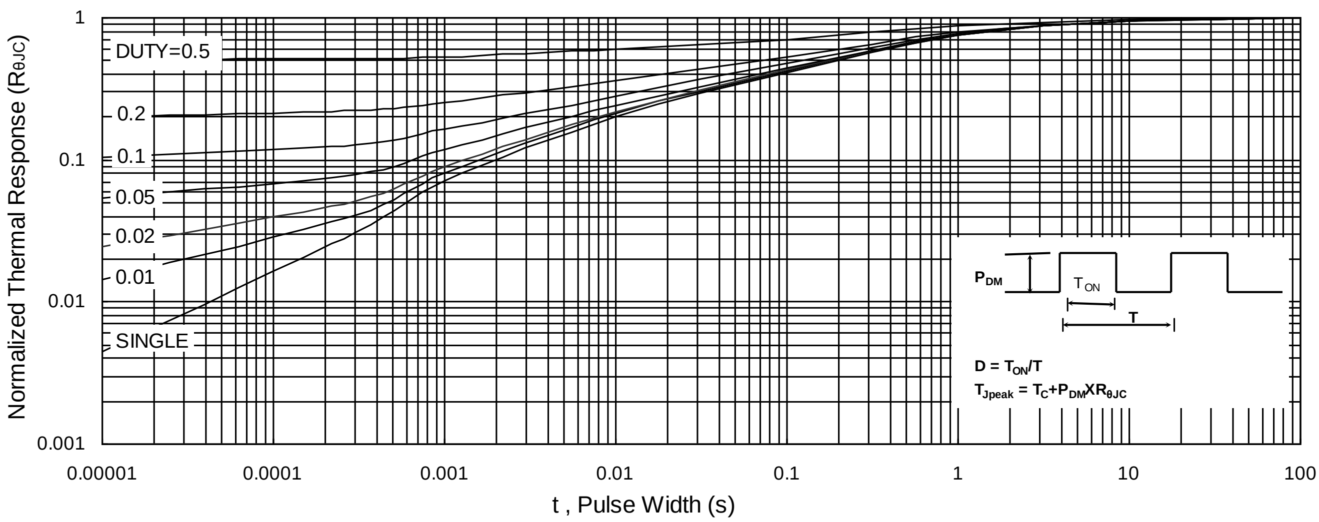


Fig.9 Normalized Maximum Transient Thermal Impedance

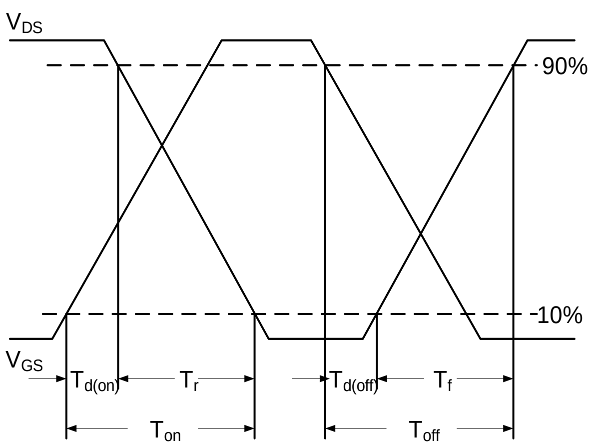


Fig.10 Switching Time Waveform

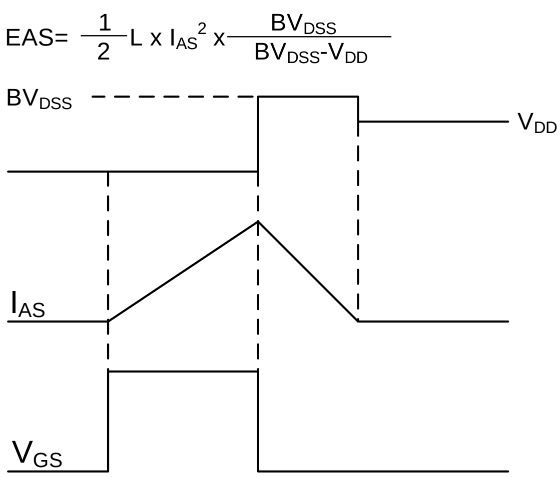
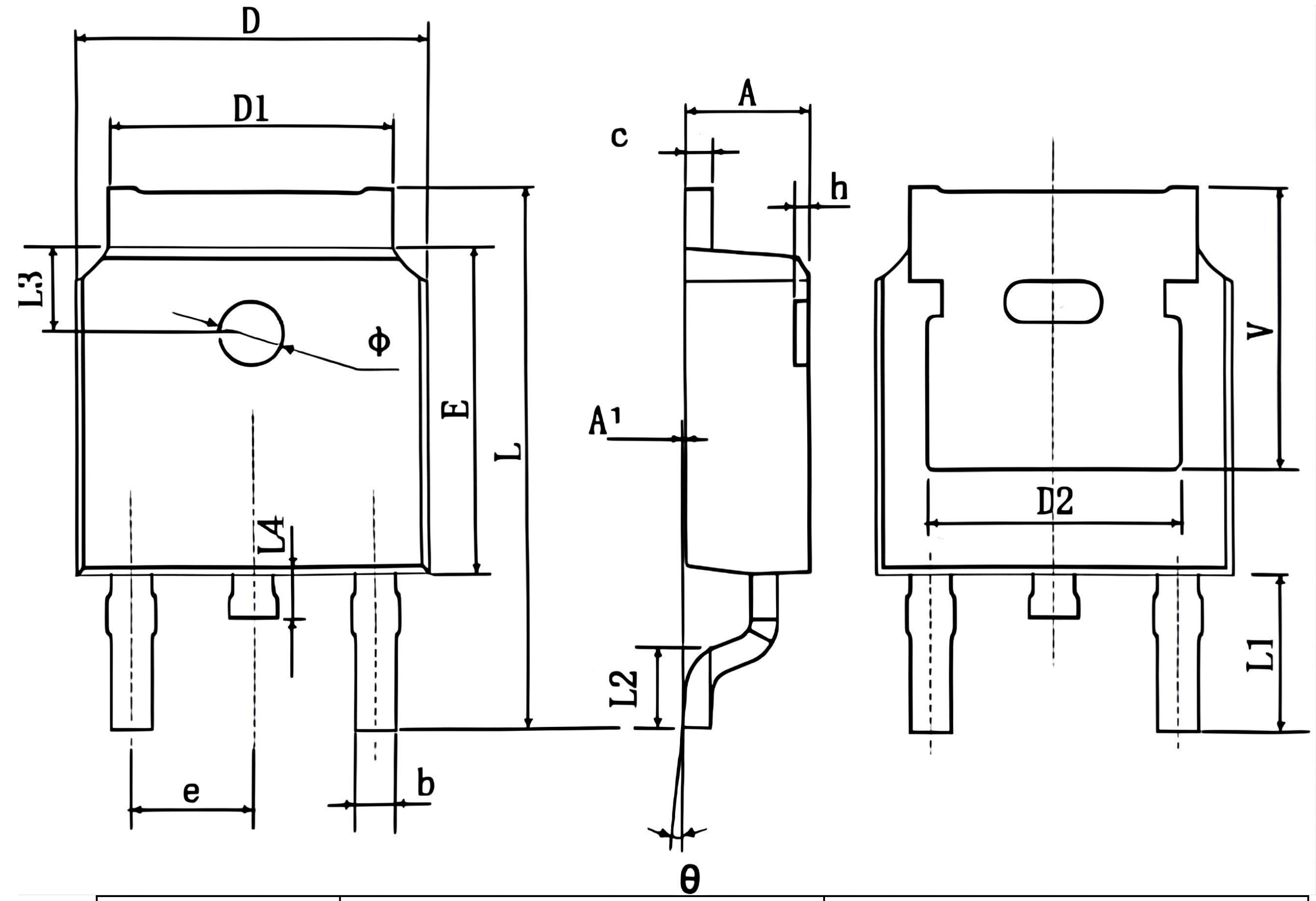


Fig.11 Unclamped Inductive Switching Waveform

Package Information

TO252-2L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	0.483 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	

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